

## Electronic Patent Application Fee Transmittal

Application Number:	10581395			
Filing Date:	14-Aug-2008			
Title of Invention:	Chip Scale Package and Method of Assembling the Same			
First Named Inventor/Applicant Name:	Hien Boon Tan			
Filer:	Carl Joseph Pellegrini/ruth swanson			
Attorney Docket Number:	Q78657			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>